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Semiconductor Wafer Polishing and Grinding Equipment Market Report by Type (Semiconductor Wafer Polishing Equipment, Semiconductor Wafer Grinding Equipment), End User (Foundries, Memory Manufacturers, IDMs, and Others), and Region 2024-2032

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Abstracts

The global semiconductor wafer polishing and grinding equipment market size reached US$ 431.2 Million in 2023. Looking forward, IMARC Group expects the market to reach US$ 647.8 Million by 2032, exhibiting a growth rate (CAGR) of 4.5% during 2024-2032.

Polishing and grinding equipment refer to advanced, indispensable components generally used while fabricating semiconductor wafers. They involve deposition, lithography, Ion implant, etching, and cleaning as some of the standard methods performed with the assistance of metallographic tools, disc finishing, and lapping machines. Semiconductor wafer polishing and grinding equipment aid in removing unwarranted material from a film and thinning and refining the product while ensuring a smooth and damage-free surface. On account of these properties, they are extensively utilized by foundries and memory manufacturers for composing integrated circuits.

Semiconductor Wafer Polishing and Grinding Equipment Market Trends:
With the rapid expansion in the electronics industry, there has been increasing demand for microelectromechanical systems (MEMS), microchips and integrated circuits for manufacturing various consumer electronic goods, including smartphones, laptops and desktops. This, in turn, has facilitated the widespread adoption of advanced semiconductor wafer grinding and polishing machinery for thinning and mitigating damage from wafers, which represents one of the prime factors currently driving the

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market growth. In line with this, significant technological advancements, such as the employment of metal-oxide-semiconductor (MOS) and chemical-mechanical-polishing (CMP) solutions to maintain the wafer surface profile during production processes, are acting as other growth-inducing factors. The market is also being supported by the large-scale integration of wireless technologies, including the Internet of Things (IoT) and artificial intelligence (AI), that help manufacturers engineer smart devices. Additionally, the extensive utilization of polishing and grinding equipment in wafer fabrication plants to manufacture a system on a chip (SoC) dice is contributing to the market growth. Other factors, such as the rising need for miniaturized electronic devices with thinner wafers, continuous investments in research and development (R&D) activities, and strategic collaborations amongst key players to introduce high-performance wafer polishing and grinding tools are creating a positive outlook for the market.

Key Market Segmentation:
IMARC Group provides an analysis of the key trends in each sub-segment of the global semiconductor wafer polishing and grinding equipment market report, along with forecasts at the global, regional and country level from 2024-2032. Our report has categorized the market based on type and end user.

Breakup by Type:

Semiconductor Wafer Polishing Equipment
Semiconductor Wafer Grinding Equipment

Breakup by End User:

Foundries
Memory Manufacturers
IDMs
Others

Breakup by Region:

North America
United States
Canada
Asia-Pacific
China

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Japan
India
South Korea
Australia
Indonesia
Others
Europe
Germany
France
United Kingdom
Italy
Spain
Russia
Others
Latin America
Brazil
Mexico
Others
Middle East and Africa

Competitive Landscape:
The competitive landscape of the industry has also been examined along with the profiles of the key players being Accretech (Europe) Gmbh (Tokyo Seimitsu Co. Ltd.), Amtech Systems Inc., Axus Technology, BBS Kinmei Co Ltd, Disco Corporation, Dynavest Pte Ltd, Ebara Corporation, Gigamat Technologies Inc., Lapmaster Wolters GmbH (Lapmaster International LLC), Logitech Ltd., Okamoto Machine Tool Works Ltd and Revasum Inc.

Key Questions Answered in This Report:
How has the global semiconductor wafer polishing and grinding equipment market performed so far and how will it perform in the coming years?
What has been the impact of COVID-19 on the global semiconductor wafer polishing and grinding equipment market?
What are the key regional markets?
What is the breakup of the market based on the type?
What is the breakup of the market based on the end user?
What are the various stages in the value chain of the industry?
What are the key driving factors and challenges in the industry?
What is the structure of the global semiconductor wafer polishing and grinding

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equipment market and who are the key players?
What is the degree of competition in the industry?

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